



Material Content Data Sheet



Sales Product Name		BFP 196 WN H6327		Issued		25. January 2018		
MA#		MA001643808						
Package		PG-SOT343-4-1		Weight*		6.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.04		432	
	non noble metal	tin	7440-31-5	0.001	0.01		111	
	inorganic material	silicon	7440-21-3	0.025	0.37	0.42	3725	4268
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		499	
	non noble metal	chromium	7440-47-3	0.010	0.15		1497	
	non noble metal	copper	7440-50-8	3.347	49.69	49.90	496824	498920
wire	noble metal	gold	7440-57-5	0.012	0.17	0.17	1725	1725
encapsulation	organic material	carbon black	1333-86-4	0.031	0.46		4560	
	plastics	epoxy resin	-	0.661	9.80		98048	
	inorganic material	silicondioxide	60676-86-0	2.381	35.34	45.60	353427	456035
leadfinish	non noble metal	tin	7440-31-5	0.199	2.96	2.96	29571	29571
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9481	9481
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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